



SAMSUNG
ELECTRO-MECHANICS

Metal Composite Power Inductor (Thin Film)

Specification Sheet



CIGT252010LM2R2MNE (2520 / EIA 1008)



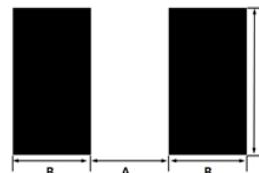
APPLICATION

Smart phones, Tablet, Wearable devices, Power converter modules, etc.

FEATURES

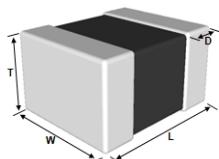
Small power inductor for mobile devices
Low DCR structure and high efficiency inductor for power circuits.
Monolithic structure for high reliability
Free of all RoHS-regulated substances
Halogen free

RECOMMENDED LAND PATTERN



Unit : mm	
TYPE	2520
A	1.2
B	0.8
C	2.0

DIMENSION



TYPE	Dimension [mm]			
	L	W	T	D
2520	2.5±0.2	2.0±0.2	1.0 max	0.55±0.25

DESCRIPTION

Part no.	Size [inch/mm]	Thickness [mm] (max)	Inductance [uH]	Inductance tolerance (%)	DC Resistance [mΩ]		Rated DC Current (Isat) [A]		Rated DC Current (Irms) [A]	
					Max.	Typ.	Max.	Typ.	Max.	Typ.
CIGT252010LM2R2MNE	1008/2520	1.0	2.2	±20	97	81	2.3	2.8	2.1	2.5

* Inductance : Measured with a LCR meter 4991A(Agilent) or equivalent (Test Freq. 1MHz, Level 0.1V)

* DC Resistance : Measured with a Resistance HI-TESTER 3541(HIOOKI) or equivalent

* Maximum allowable DC current : Value defined when DC current flows and the initial value of inductance has decreased by 30% or when current flows and temperature has risen to 40°C whichever is smaller. (Reference: ambient temperature is 25°C±10)

(Isat) : Allowable current in DC saturation : The DC saturation allowable current value is specified when the decrease of the initial inductance value at 30% (Reference: ambient temperature is 25°C±10)

(Irms) : Allowable current of temperature rise : The temperature rise allowable current value is specified when temperature of the inductor is raised 40°C by DC current. (Reference: ambient temperature is 25°C±10)

* Absolute maximum voltage : Absolute maximum voltage DC 20V.

* Operating temperature range : -40 to +125°C (Including self-temperature rise)

PRODUCT IDENTIFICATION

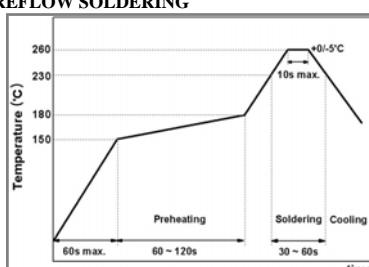
CIG **T** **2520** **10** **LM** **2R2** **M** **N** **E**
(1) **(2)** **(3)** **(4)** **(5)** **(6)** **(7)** **(8)** **(9)**

(1) Power Inductor
 (3) Dimension (2520: 2.5mm x 2.0mm)
 (5) Remark (Characterization Code)
 (7) Toleranc (M:±20%)
 (8) Internal Code
 (9) Packaging (C:paper tape, E:embossed tape)

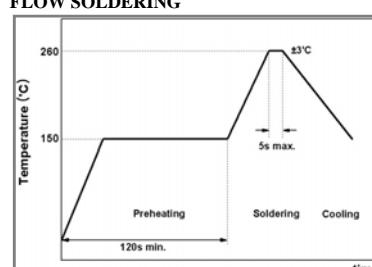
(2) Type (T: Metal Composite Thin Film Type)
 (4) Thicknes (10: 1.0mm)
 (6) Inductan (2R2: 2.2 uH)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



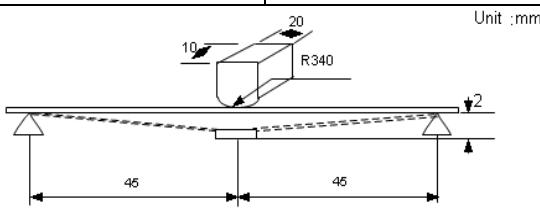
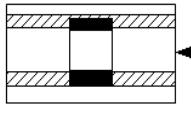
IRON SOLDERING

Temperature of Soldering Iron Tip	280 °C max.
Preheating Temperature	150 °C min.
Temperature Differential	$\Delta T \leq 130$ °C
Soldering Time	3sec max.
Wattage	50W max.

PACKAGING

Packaging Style	Quantity(pcs/reel)
Embossed Taping	3000 pcs

Reliability Test

Item	Specified Value	Test Condition				
Solderability	More than 90% of terminal electrode should be soldered newly.	After being dipped in flux for 4 ± 1 seconds, and preheated at $150\sim180^\circ\text{C}$ for $2\sim3$ min, the specimen shall be immersed in solder at $245\pm5^\circ\text{C}$ for 4 ± 1 seconds.				
Resistance to Soldering	No mechanical damage. Remaining terminal Electrode: 75% min. Inductance change to be within $\pm20\%$ to the initial.	After being dipped in flux for 4 ± 1 seconds, and preheated at $150\sim180^\circ\text{C}$ for $2\sim3$ min, the specimen shall be immersed in solder at $260\pm5^\circ\text{C}$ for 10 ± 0.5 seconds.				
Thermal Shock (Temperature Cycle test)	No mechanical damage Inductance change to be within $\pm20\%$ to the initial.	Repeat 100 cycles under the following conditions. $-40\pm3^\circ\text{C}$ for 30 min $\rightarrow 85\pm3^\circ\text{C}$ for 30 min				
High Temp. Humidity Resistance Test	No mechanical damage Inductance change to be within $\pm20\%$ to the initial	$85\pm2^\circ\text{C}$, 85%RH, for 500 ± 12 hours. Measure the test items after leaving at normal temperature and humidity for 24 hours.				
Low Temperature Test	No mechanical damage Inductance change to be within $\pm20\%$ to the initial	Solder the sample on PCB. Exposure at $-55\pm2^\circ\text{C}$ for 500 ± 12 hours. Measure the test items after leaving at normal temperature and humidity for 24 hours.				
High Temperature Test	No mechanical damage Inductance change to be within $\pm20\%$ to the initial	Solder the sample on PCB. Exposure at $125\pm2^\circ\text{C}$ for 500 ± 12 hours. Measure the test items after leaving at normal temperature and humidity for 24 hours.				
High Temp. Humidity Resistance Loading Test	No mechanical damage Inductance change to be within $\pm20\%$ to the initial	$85\pm2^\circ\text{C}$, 85%RH, Rated Current for 500 ± 12 hours. Measure the test items after leaving at normal temperature and humidity for 24 hours.				
High Temperature Loading Test	No mechanical damage Inductance change to be within $\pm20\%$ to the initial	$85\pm2^\circ\text{C}$, Rated Current for 500 ± 12 hours. Measure the test items after leaving at normal temperature and humidity for 24 hours.				
Reflow Test	No mechanical damage Inductance change to be within $\pm20\%$ to the initial	Peak $260\pm5^\circ\text{C}$, 3 times				
Vibration Test	No mechanical damage Inductance change to be within $\pm20\%$ to the initial	Solder the sample on PCB. Vibrate as apply 10~55Hz, 1.5mm amplitude for 2 hours in each of three(X,Y,Z) axis (total 6 hours).				
Bending Test	No mechanical damage	Bending Limit: 2mm Test Speed: 1.0mm/sec. Keep the test board at the limit point in 5 sec. PCB thickness : 1.6mm				
						
Terminal Adhesion Test	No indication of peeling shall occur on the terminal electrode.	<table border="1"> <thead> <tr> <th>W(kgf)</th> <th>TIME(sec)</th> </tr> </thead> <tbody> <tr> <td>0.5</td> <td>10 ± 1</td> </tr> </tbody> </table>	W(kgf)	TIME(sec)	0.5	10 ± 1
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0.5	10 ± 1					
						
Drop Test	No mechanical damage Inductance change to be within $\pm20\%$ to the initial.	Random Free Fall test on concrete plate. 1 meter, 10 drops				
Ipeak (AC+DC Load Life)	No mechanical damage Inductance change to be within $\pm20\%$ to the initial	$85\pm2^\circ\text{C}$, 85%RH, Load(Ipeak) for 120 hours. (Frequency:1MHz, Load(Ipeak):1.5hr on / 0.5hr off) Measure the test items after leaving at normal temperature and humidity for 24 hours. * Load(Ipeak) = $Irms(max) \times 1.4$				



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Data Sheet



1. Model : CIGT252010LM2R2MNE

2. Description

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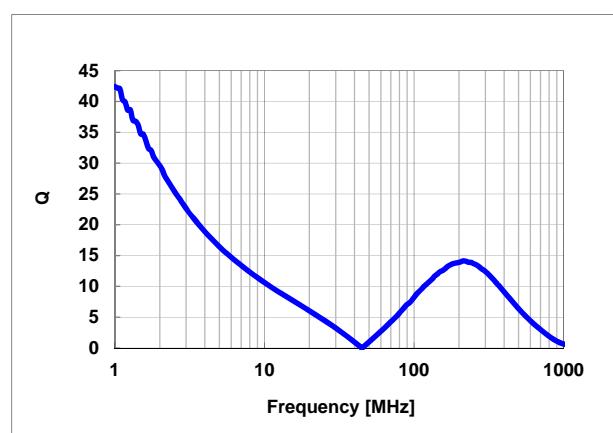
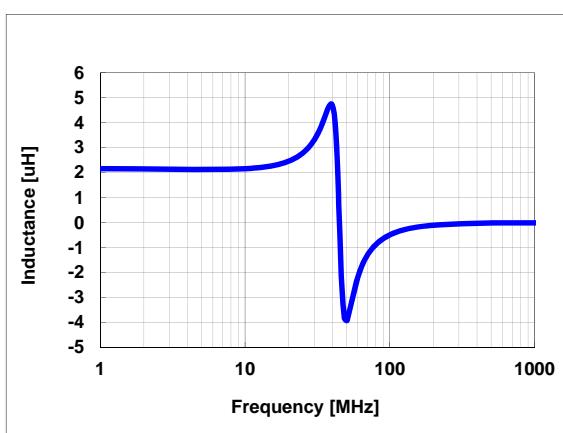
3. Characteristics data

1) Frequency characteristics (Ls)

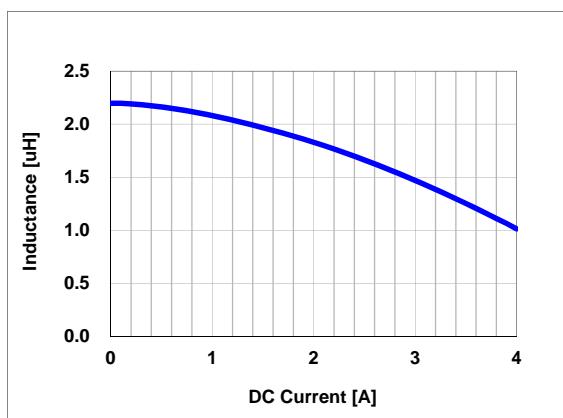
Agilent E4294A +E4991A , 1MHz to 1,000MHz

2) Frequency characteristics (Q)

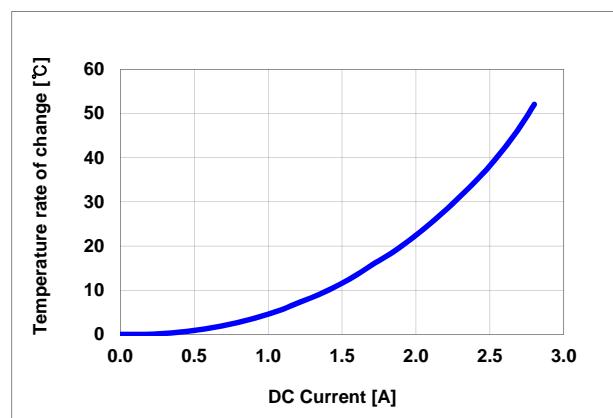
Agilent E4294A +E4991A , 1MHz to 1,000MHz



3) DC Bias characteristics (Typ.)



4) Temperature characteristics (Typ.)



Any data in this sheet are subject to change, modify or discontinue without notice

The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers